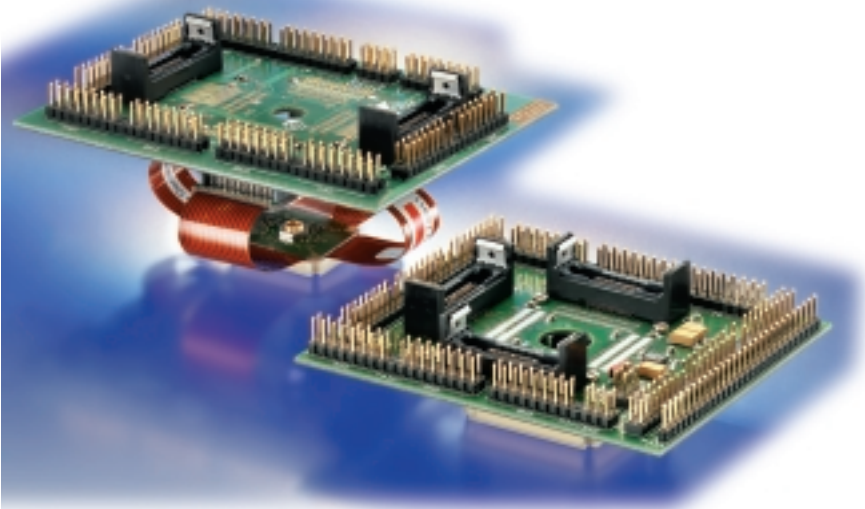


PressOn

hitex 
DEVELOPMENT TOOLS



Highlights

- Always reliable and stable connections
- Perfect for extremely flat packages with high pin count (e.g. SQFP208)
- Easy fastening and removal using simple tools (provided)
- Minimal wear, extremely long adapter life
- Minimal space requirements around soldered CPU
- No modification of the target system necessary
- Contact elements exchangeable

**Adapter
PressOn
for
Logic Analyzer
Applications**



Technical Data

Current capacity per pin:
100 mA, for an adapter's exact design and dimensions please refer to the technical data sheet.

Requirements on the target system:

- 2 mm free space around the device on the target board
- Prior to mounting, all pins must be correctly soldered and cleaned of all flux or other residue
- Sufficient vertical clearance for adapter and emulator probe above the CPU. See individual specifications.

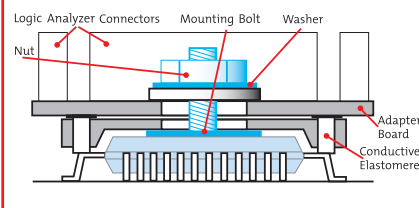
Contents of PressOn adapter set:

- PressOn adapter
- Mounting material (studs and nuts)
- Special adhesive
- Miniature socket wrench
- Installation guide
- Cleaning accessories

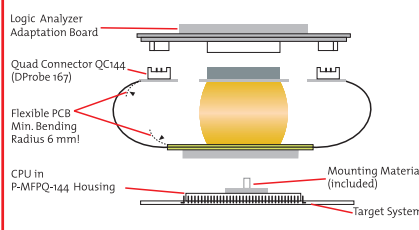
Supported package types:

- MQFP80 (20 x 20 0.65mm)
- MQFP100 (30 x 20 0.65mm)
- TQFP100 (25 x 25 0.5mm)
- TQFP128 (32 x 32 0.5mm)
- TQFP144 (36 x 36 0.5mm)
- PQFP132 (33 x 33 0.65mm)
- MQFP144 (36 x 36 0.65mm)
- MQFP160 (40x 40 0.65mm)
- TQFP176 (44 x 44 0.5mm)
- SQFP208 (52 x 52 0.5mm 3.5mm high)
- LQFP208 (52 x 52 0.5mm 1.2mm high)

Adaptation Principle



Example of a PressOn for MQFP144 package



Innovative Adaptation Technology for Logic Analyzers

Until now, there has been no satisfactory method for connecting test equipment to microprocessors and controllers in soldered-in QFP packages.

Traditional methods for connecting a Logic Analyzer to a system under test require mechanical accommodation on the target system; these methods, however, are not always practical. To solve this problem, Hitex developed an innovative method for connecting to such devices - the patented PressOn adapter.

The PressOn adapter provides a reliable electrical and mechanical connection to all pins of a soldered-in chip, even where inter-chip space is limited. PressOn technology utilizes two clever concepts.

- Elastic silicon strips carry a multitude of ultra-fine gold wires that make reliable electrical contact; and

- A small stud, temporarily bonded to the IC package, provides a means for securing the gold-bearing elastomer strips.

The PressOn adapter conducts all signals reliably and with minimal degradation. It provides a uniform and stable connection to all pins. When traditional adaptation methods cannot be used, the PressOn adapter provides a foolproof connection. Even for ultra-flat packages that have a pin-pitch as small as 0.4-mm, or for PC boards right out of production, the PressOn adapter is the perfect choice.

Installation is simple. After thoroughly cleaning the IC's pins, the user, using special adhesive, bonds the stud to the package. The adapter is then pressed onto the contacts with a small nut. Because it is easily removed from the chip after testing, this adapter can be used many times. The uniform pressure on every pin and the redundant gold wires assure maximum conductivity and many reliable connections for the life of the product.

All Hitex PressOn adapters basically provide generic 1:1 connections with standardized "QuadConnector" interfaces. The adaptation for specific devices and test equipment is done with conversion boards designed to customer specifications. Those boards can either be designed by Hitex or by the customer as the specifications for the interfaces are available from Hitex. All PressOn adapters without conversion boards are separately available as "Generic Adapters". Datasheets & drawings can be found in the Online Documentation at www.hitex.com or on the Hitex CDRom. For questions concerning the compatibility of a PressOn adapter with a specific device or package not listed here please contact Hitex.



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